

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A package for a semiconductor device comprising:
a semiconductor die having a laterally conducting structure and a ground contact
on an upper surface; and

a leadframe comprising,

a diepad in contact with a lower surface of the die,

a lead separated from the diepad, and

a supplemental downbond diepad portion projecting from a main portion
of the diepad and configured to receive a downbond wire from the ground contact, the
supplemental diepad portion positioned between an end of the package and the die, and
between the lead and a second lead that is also separate from the diepad.

2-4. (Canceled)

5. (Original) The package of claim 1 comprising more than one
supplemental downbond portion.

6. (Original) The package of claim 1 wherein the die comprises a power IC
die.

7. (Original) The package of claim 1 wherein the die is configured to
operate with a current of between about 1 and 20 Amps.

8. (Original) The package of claim 1 wherein the die is selected from the
group consisting of an integrated circuit, a JFET, and a lateral MOSFET.

9. (Original) The package of claim 1 wherein the diepad comprises copper.

10.-16 (Canceled)